

Form PTO-1598 (Rev. 03/04)
OMB No. 0651-0027 (exp. 6/30/2006)

U.S. Department of COMMERCE
United States Patent and Trademark Office

RECORDATION FORM COVER SHEET PATENTS ONLY

To the Director of the U.S. Patents and Trademark Office: Please record the attached documents or the new address(es) below.

1. Name of conveying party(ies):

KAUSHAL K. SINGH
PAUL B. COMITA
LANCE A. SCUDDER
DAVID K. CARLSON

June 24, 2004
February 6, 2004
June 23, 2004
January 29, 2004

Additional name of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of conveyance:

Execution Date(s) _____

- ☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Government Interest Assignment
☐ Executive Order 9424, Confirmatory License
☐ Other

2. Name and address of receiving party(ies)

Name: APPLIED MATERIALS, INC.

Internal Address: Patent Counsel

Street Address: P.O. Box 450-A

City: Santa Clara

State: CA

Country: USA

Zip: 95052

Additional Name(s) & address(es) attached? ☐ Yes ☒ No

4. Application number(s) or patent number(s):

A. Patent Application No.(s)

11/549,033; Filed October 12, 2006

☐ This document is being filed together with a new application.

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning this document should be mailed:

Name: Patterson & Sheridan, L.L.P.

Internal Address: Applied Materials, Inc.

Street Address: 3040 Post Oak Boulevard, Suite 1500

City: Houston

State: TX

Zip: 77056

Phone Number: 713-623-4844

Fax Number: 713-623-4846

Email Address: tpatterson@pattersonsheridan.com

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 1.21(h) & 3.41)

\$ 40.00

- ☐ Authorized to be charged by credit card
☒ Authorized to be charged to deposit account
☐ Enclosed
☐ None required (government interest not affecting title)

8. Payment Information

a. Credit Card Last 4 Numbers
Expiration Date _____

b. Deposit Account Number
50-1074/007729.C1/TCG/EPI/AG

Authorized User Name Robert W. Mulcahy

9. Signature:

Signature

October 18, 2006

Date

Robert W. Mulcahy - Reg No. 25,436

Name of Person Signing

Total number of pages, sheet, attachments,
and documents including cover

7

Documents to be recorded (including cover sheet) should be faxed to (703) 308-5998, or mailed to:
Mail Stop Assignment Recordation Services, Director of the USPTO, P.O.Box 1460, Alexandria, V.A. 22313-1460

CH \$40.00 501074 11549033

Atty. Dkt. No. APPM/7729/TCG/EPI/RKK

ASSIGNMENT FOR APPLICATION FOR PATENT**WHEREAS:**

Names and Addresses of Inventors:

1)	KAUSHAL K. SINGH 2118 San Rafael Avenue Santa Clara, CA 95051	2)	PAUL B. COMITA 350 Hermosa Way Menlo Park, CA 94025
3)	LANCE A. SCUDDER 795 Orkney Avenue Santa Clara, CA 95054	4)	DAVID K. CARLSON 2308 Dundee Drive Santa Clara, CA 95051

(hereinafter referred to as Assignors), have invented a certain invention entitled:

SILICON-CONTAINING LAYER DEPOSITION WITH SILICON COMPOUNDS

enclosed herewith or for which application for Letters Patent in the United States was filed on October 17, 2003, under Serial No. 10/688,797, executed on even date herewith; and

WHEREAS, Applied Materials, Inc., a corporation of the State of Delaware, having a place of business at 3050 Bowers Avenue, Santa Clara, California 95054 (hereinafter referred to as Assignee), is desirous of acquiring the entire right, title and interest in and to said application (hereinafter referred to as Application), and the invention disclosed therein (hereinafter referred to as Invention), and in and to all embodiments of the Invention, heretofore conceived, made or discovered by said Assignors, and in and to any and all patents, inventor's certificates and other forms of protection (hereinafter referred to as Patents) thereon granted in any and all countries and groups of countries.

NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Assignors to have been received in full from said Assignee:

1. Said Assignors hereby sell, assign, transfer and convey to Assignee the full and exclusive right, title and interest (a) in and to said Application and said Invention; (b) in and to all rights to apply for patents on said Invention in any and all countries pursuant to the International Convention for the Protection of Industrial Property or otherwise; (c) in and to any and all Applications filed and any and all Patents granted on said Invention in any and all countries and groups of countries, including each and every Application filed and each and every Patent granted on any application which is a division, substitution, or continuation of said Application; and (d) in and to each and every reissue or extension of any of said Patents.

2. Said Assignors hereby covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest to said Invention herein conveyed in any and all countries and groups of

countries. Such cooperation by said Assignors shall include prompt production of pertinent facts and documents, giving testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for prosecuting any of said applications; (c) for filing and prosecuting substitute, divisional, continuing or additional applications covering said Invention; (d) for filing and prosecuting applications for reissuance of any of said Patents; (e) for interference or other priority proceedings involving said Invention; and (f) for legal proceedings involving said Invention and any application therefor and any Patents granted thereon, including without limitation opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Assignors in providing such cooperation shall be paid for by said Assignee.

3. The term and covenants of this agreement shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Assignors, their respective heirs, legal representatives and assigns.

4. Said Assignors hereby warrant and represent that they have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

IN WITNESS WHEREOF, the said Assignors have executed and delivered this instrument to said Assignee on the dates indicated below.

1)	<u>6/24/04</u> (DATE)	<u>KK Singh</u> KAUSHAL K. SINGH
2)	_____ (DATE)	_____ PAUL B. COMITA
3)	_____ (DATE)	_____ LANCE A. SCUDDER
4)	<u>1/29/04</u> (DATE)	<u>David K. Carlson</u> DAVID K. CARLSON

Atty. Dkt. No. APPM/7729/TCG/EPI/RKK

ASSIGNMENT FOR APPLICATION FOR PATENT

WHEREAS:

Names and Addresses of Inventors:

1)	KAUSHAL K. SINGH 2118 San Rafael Avenue Santa Clara, CA 95051	2)	PAUL B. COMITA 350 Hermosa Way Menlo Park, CA 94025
3)	LANCE A. SCUDDER 795 Orkney Avenue Santa Clara, CA 95054	4)	DAVID K. CARLSON 2308 Dundee Drive Santa Clara, CA 95051

(hereinafter referred to as Assignors), have invented a certain invention entitled:

SILICON-CONTAINING LAYER DEPOSITION WITH SILICON COMPOUNDS

enclosed herewith or for which application for Letters Patent in the United States was filed on October 17, 2003, under Serial No. 10/688,797, executed on even date herewith; and

WHEREAS, Applied Materials, Inc., a corporation of the State of Delaware, having a place of business at 3050 Bowers Avenue, Santa Clara, California 95054 (hereinafter referred to as Assignee), is desirous of acquiring the entire right, title and interest in and to said application (hereinafter referred to as Application), and the invention disclosed therein (hereinafter referred to as Invention), and in and to all embodiments of the Invention, heretofore conceived, made or discovered by said Assignors, and in and to any and all patents, inventor's certificates and other forms of protection (hereinafter referred to as Patents) thereon granted in any and all countries and groups of countries.

NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Assignors to have been received in full from said Assignee:

1. Said Assignors hereby sell, assign, transfer and convey to Assignee the full and exclusive right, title and interest (a) in and to said Application and said Invention; (b) in and to all rights to apply for patents on said Invention in any and all countries pursuant to the International Convention for the Protection of Industrial Property or otherwise; (c) in and to any and all Applications filed and any and all Patents granted on said Invention in any and all countries and groups of countries, including each and every Application filed and each and every Patent granted on any application which is a division, substitution, or continuation of said Application; and (d) in and to each and every reissue or extension of any of said Patents.

2. Said Assignors hereby covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest to said Invention herein conveyed in any and all countries and groups of

countries. Such cooperation by said Assignors shall include prompt production of pertinent facts and documents, giving testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for prosecuting any of said applications; (c) for filing and prosecuting substitute, divisional, continuing or additional applications covering said Invention; (d) for filing and prosecuting applications for reissuance of any of said Patents; (e) for interference or other priority proceedings involving said Invention; and (f) for legal proceedings involving said Invention and any application therefor and any Patents granted thereon, including without limitation opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Assignors in providing such cooperation shall be paid for by said Assignee.

3. The term and covenants of this agreement shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Assignors, their respective heirs, legal representatives and assigns.

4. Said Assignors hereby warrant and represent that they have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

IN WITNESS WHEREOF, the said Assignors have executed and delivered this instrument to said Assignee on the dates indicated below.

1)	_____ (DATE)	_____
		KAUSHAL K. SINGH
2)	<u>Feb 6, 2004</u> (DATE)	_____
		PAUL B. COMITA
3)	_____ (DATE)	_____
		LANCE A. SCUDDER
4)	_____ (DATE)	_____
		DAVID K. CARLSON

Atty. Dkt. No. APPM/7729/TCG/EPI/RKK

ASSIGNMENT FOR APPLICATION FOR PATENT**WHEREAS:**

Names and Addresses of Inventors:

1)	KAUSHAL K. SINGH 2118 San Rafael Avenue Santa Clara, CA 95051	2)	PAUL B. COMITA 350 Hermosa Way Menlo Park, CA 94025
3)	LANCE A. SCUDDER 6000 Scenic Meadow Lane San Jose, CA 95135	4)	DAVID K. CARLSON 2308 Dundee Drive Santa Clara, CA 95051

(hereinafter referred to as Assignors), have invented a certain invention entitled:

SILICON-CONTAINING LAYER DEPOSITION WITH SILICON COMPOUNDS

enclosed herewith or for which application for Letters Patent in the United States was filed on October 17, 2003, under Serial No. 10/688,797, executed on even date herewith; and

WHEREAS, Applied Materials, Inc., a corporation of the State of Delaware, having a place of business at 3050 Bowers Avenue, Santa Clara, California 95054 (hereinafter referred to as Assignee), is desirous of acquiring the entire right, title and interest in and to said application (hereinafter referred to as Application), and the invention disclosed therein (hereinafter referred to as Invention), and in and to all embodiments of the Invention, heretofore conceived, made or discovered by said Assignors, and in and to any and all patents, inventor's certificates and other forms of protection (hereinafter referred to as Patents) thereon granted in any and all countries and groups of countries.

NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Assignors to have been received in full from said Assignee:

1. Said Assignors hereby sell, assign, transfer and convey to Assignee the full and exclusive right, title and interest (a) in and to said Application and said Invention; (b) in and to all rights to apply for patents on said Invention in any and all countries pursuant to the International Convention for the Protection of Industrial Property or otherwise; (c) in and to any and all Applications filed and any and all Patents granted on said Invention in any and all countries and groups of countries, including each and every Application filed and each and every Patent granted on any application which is a division, substitution, or continuation of said Application; and (d) in and to each and every reissue or extension of any of said Patents.


2. Said Assignors hereby covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest to said Invention herein conveyed in any and all countries and groups of

countries. Such cooperation by said Assignors shall include prompt production of pertinent facts and documents, giving testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for prosecuting any of said applications; (c) for filing and prosecuting substitute, divisional, continuing or additional applications covering said Invention; (d) for filing and prosecuting applications for reissuance of any of said Patents; (e) for interference or other priority proceedings involving said Invention; and (f) for legal proceedings involving said Invention and any application therefor and any Patents granted thereon, including without limitation opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Assignors in providing such cooperation shall be paid for by said Assignee.

3. The term and covenants of this agreement shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Assignors, their respective heirs, legal representatives and assigns.

4. Said Assignors hereby warrant and represent that they have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

IN WITNESS WHEREOF, the said Assignors have executed and delivered this instrument to said Assignee on the dates indicated below.

1)	_____ (DATE)	_____
		KAUSHAL K. SINGH
2)	_____ (DATE)	_____
		PAUL B. COMITA
3)	<u>6-23-04</u> (DATE)	
		LANCE A. SCUDDER
4)	_____ (DATE)	_____
		DAVID K. CARLSON